Zilog - Z8PE002HZ010SC00TR Datasheet

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	10MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	14
Program Memory Size	512B (512 x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	64 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z8pe002hz010sc00tr

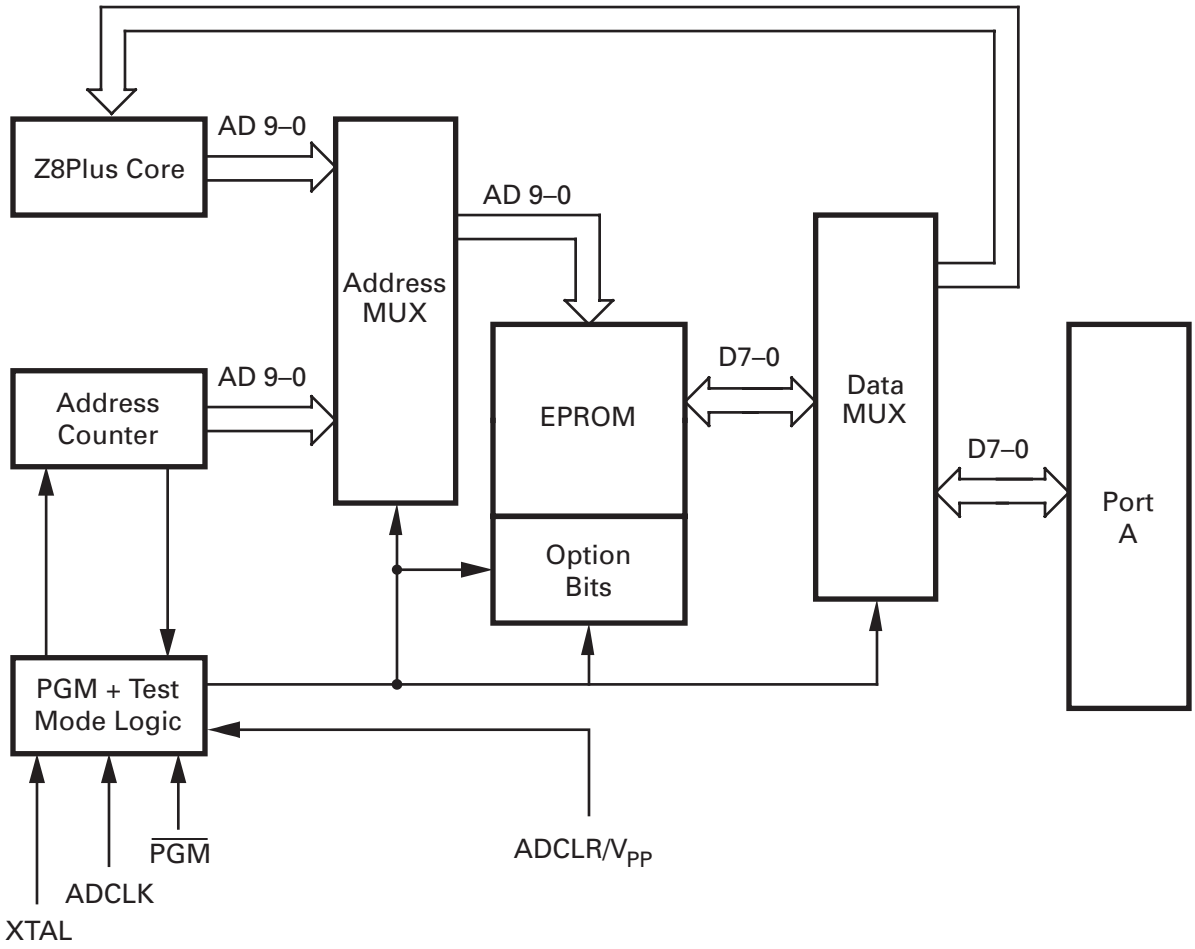


Figure 2. EPROM Programming Mode Block Diagram

PIN DESCRIPTION

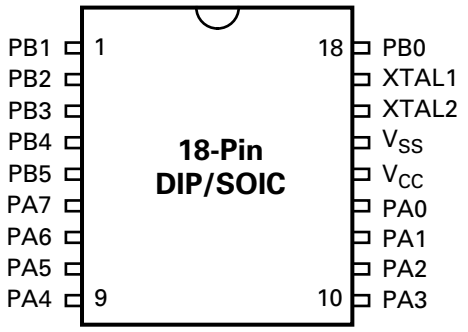


Figure 3. 18-Pin DIP/SOIC Pin Identification

Table 1. Standard Programming Mode

Pin #	Symbol	Function	Direction
1–5	PB1–PB5	Port B, Pins 1,2,3,4,5	Input/Output
6–9	PA7–PA4	Port A, Pins 7,6,5,4	Input/Output
10–13	PA3–PA0	Port A, Pins 3,2,1,0	Input/Output
14	V_{CC}	Power Supply	
15	V_{SS}	Ground	
16	XTAL2	Crystal Oscillator Clock	Output
17	XTAL1	Crystal Oscillator Clock	Input
18	PB0	Port B, Pin 0	Input/Output

ABSOLUTE MAXIMUM RATINGS

Parameter	Min	Max	Units	Note
Ambient Temperature under Bias	–40	+105	C	
Storage Temperature	–65	+150	C	
Voltage on any Pin with Respect to V_{SS}	–0.6	+7	V	1
Voltage on V_{DD} Pin with Respect to V_{SS}	–0.3	+7	V	
Voltage on PB5 Pin with Respect to V_{SS}	–0.6	V_{DD}+1	V	2
Total Power Dissipation		880	mW	
Maximum Allowable Current out of V_{SS}		40	mA	3
Maximum Allowable Current into V_{DD}		40	mA	3
Maximum Allowable Current into an Input Pin	–600	+600	µA	4
Maximum Allowable Current into an Open-Drain Pin	–600	+600	µA	5
Maximum Allowable Output Current Sunk by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sourced by Any I/O Pin		25	mA	
Maximum Allowable Output Current Sunk by Port A		40	mA	3
Maximum Allowable Output Current Sourced by Port A		40	mA	3
Maximum Allowable Output Current Sunk by Port B		40	mA	3
Maximum Allowable Output Current Sourced by Port B		40	mA	3

Notes:
1. Applies to all pins except the PB5 pin and where otherwise noted.
2. There is no input protection diode from pin to V_{DD}.
3. Peak Current. Do not exceed 25mA average current in either direction.
4. Excludes XTAL pins.
5. Device pin is not at an output Low state.

Stresses greater than those listed under Absolute Maximum Ratings can cause permanent damage to the device. This rating is a stress rating only. Functional operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period can affect device reliability. Total power dissipation should not exceed 880 mW for the package. Power dissipation is calculated as follows:

$$\text{Total Power Dissipation} = V_{DD} \times [I_{DD} - (\text{sum of } I_{OH})] + \text{sum of } [(V_{DD} - V_{OH}) \times I_{OH}] + \text{sum of } (V_{OL} \times I_{OL})$$

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to Ground. Positive current flows into the referenced pin (Figure 7).

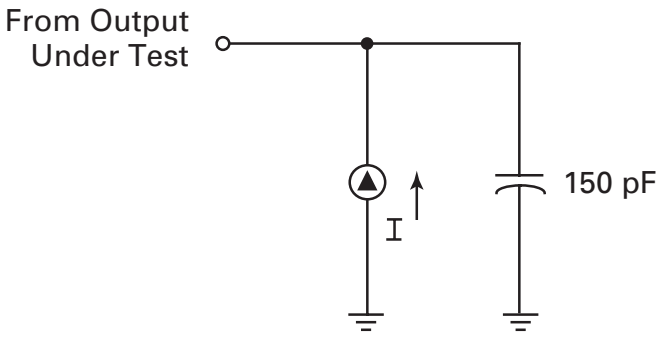


Figure 7. Test Load Diagram

CAPACITANCE

T_A = 25°C, V_{CC} = GND = 0V, f = 1.0 MHz, unmeasured pins returned to GND.

Parameter	Min	Max
Input capacitance	0	12 pF
Output capacitance	0	12 pF
I/O capacitance	0	12 pF

Table 6. DC Electrical Characteristics (Continued)

			T_A = –40°C to +105°C Extended Temperatures					
Sym	**Parameter**	**V_{CC}[1]**	**Min**	**Max**	**Typical[2] @ 25°C**	**Units**	**Conditions**	**Notes**
I_{CC1}	Standby Current	4.5V		2.0	1.0	mA	HALT mode V_{IN} = 0V, V_{CC} @ 10 MHz	5,6
		5.5V		2.0	1.0	mA	HALT mode V_{IN} = 0V, V_{CC} @ 10 MHz	5,6
I_{CC2}	Standby Current	4.5V		700	250	nA	STOP mode V_{IN} = 0V,V_{CC}	7
		5.5V		700	250	nA	STOP mode V_{IN} = 0V,V_{CC}	7

Notes:
1. The V_{CC} voltage specification of 4.5V and 5.5V guarantees 5.0V ±0.5V.
2. Typical values are measured at V_{CC} = 5.0V; V_{SS} = 0V = GND.
3. For analog comparator input when analog comparator is enabled.
4. No protection diode is provided from the pin to V_{CC}. External protection is recommended.
5. All outputs are unloaded and all inputs are at V_{CC} or V_{SS} level.
6. CL1 = CL2 = 22 pF.
7. Same as note 5, except inputs are at V_{CC}.

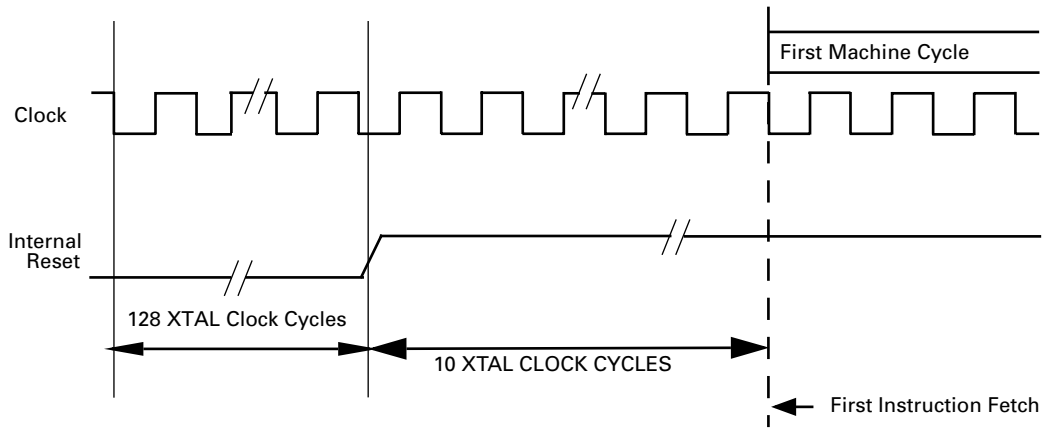


Figure 9. Reset Timing

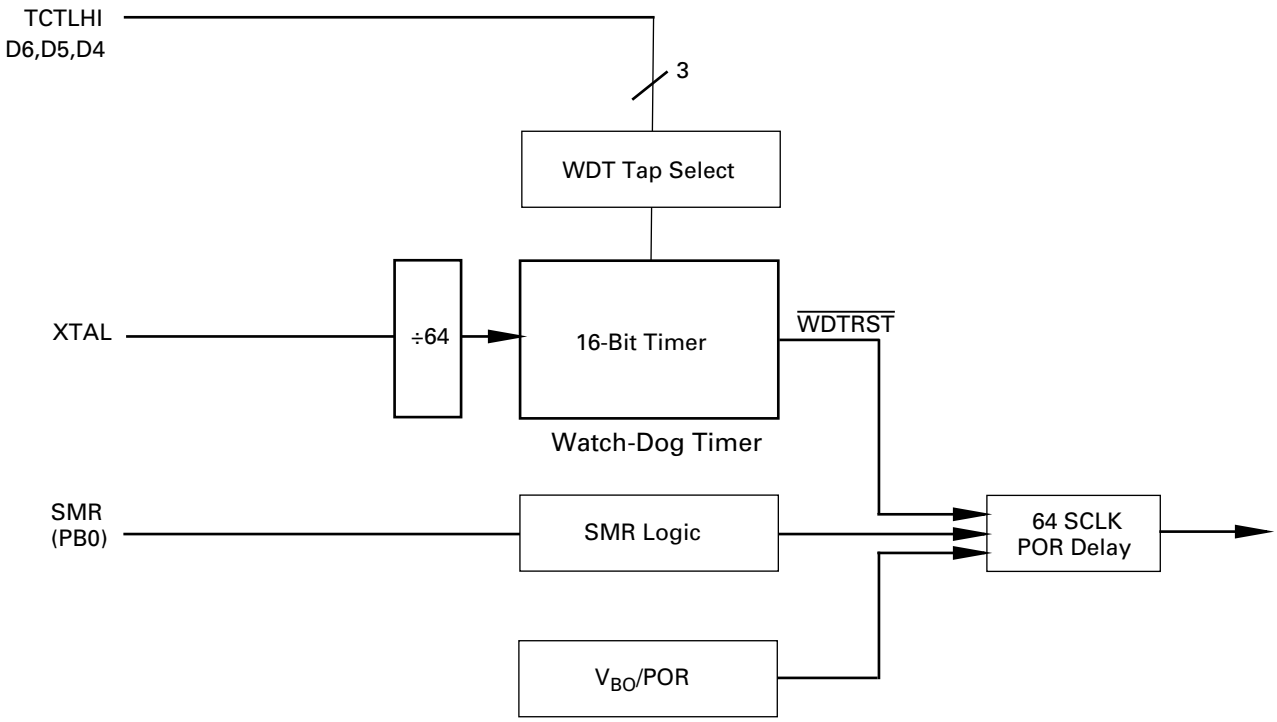


Figure 10. Reset Circuitry with POR, WDT, V_{BO}, and SMR

IREQ SOFTWARE INTERRUPT GENERATION

IREQ can be used to generate software interrupts by specifying IREQ as the destination of any instruction referencing the Z8Plus Standard Register File. These software interrupts (SWI) are controlled in the same manner as hardware generated requests. In other words, the IMASK controls the enabling of each SWI.

To generate a SWI, the request bit in IREQ is set by the following statement:

```
OR IREQ,#NUMBER
```

The immediate data variable, NUMBER, has a 1 in the bit position corresponding to the required level of SWI. For example, an SWI must be issued when an IREQ5 occurs. Bit 5 of NUMBER must have a value of 1.

```
OR IREQ, #00100000B
```

If the interrupt system is globally enabled, IREQ5 is enabled, and there are no higher priority requests pending, control is transferred to the service routine pointed to by the IREQ5 vector.

Note: Software may modify the IREQ register at any time. Care should be taken when using any instruction that modifies the IREQ register while interrupt sources are active. The software writeback always takes precedence over the hardware. If a software writeback takes place on the same cycle as an interrupt source tries to set an IREQ bit, the new interrupt is lost.

Nesting of Vectored Interrupts

Nesting vectored interrupts allows higher priority requests to interrupt a lower priority request. To initiate vectored interrupt nesting, perform the following steps during the interrupt service routine:

- PUSH the old IMASK on the stack
- Load IMASK with a new mask to disable lower priority interrupts
- Execute an EI instruction
- Proceed with interrupt processing
- Execute a DI instruction after processing is complete
- Restore the IMASK to its original value by POPing the previous mask from the stack
- Execute IRET

Depending on the application, some simplification of the above procedure may be possible.

RESET Conditions

The IMASK and IREQ registers initialize to 00h on RESET.

PROGRAMMABLE OPTIONS

EPROM Protect. When selecting the DISABLE EPROM PROTECT/ENABLE TESTMODE option, the user can read the software code in the program memory. ZiLOG's internal factory test mode, or any of the standard test mode methods, are useful for reading or verifying the code in the microcontroller when using an EPROM programmer. If the user should select the ENABLE EPROM PROTECT/DISABLE TESTMODE option, it is not possible to read the code using a tester, programmer, or any other standard method. As a result, ZiLOG is unable to test the EPROM memory at any time after customer delivery.

This option bit only affects the user's ability to read the code and has no effect on the operation of the part in an application. ZiLOG tests the EPROM memory before customer delivery whether or not the ENABLE EPROM PROTECT/DISABLE TESTMODE option is selected; ZiLOG provides a standard warranty for the part.

System Clock Source. When selecting the RC OSCILLATOR ENABLE option, the oscillator circuit on the microcontroller is configured to work with an external RC circuit. When selecting the Crystal/Other Clock Source option, the oscillator circuit is configured to work with an external crystal, ceramic resonator, or LC oscillator.

Note: The WDT can only be disabled via software if the first instruction out of the $\overline{\text{RESET}}$ performs this function. Logic within the device detects that it is in the process of executing the first instruction after the processor leaves $\overline{\text{RESET}}$. During the execution of this instruction, the upper five bits of the TCTLHI register can be written. After this first instruction, hardware does not allow the upper five bits of this register to be written.

The TCTLHI bits for control of the WDT are described below:

WDT Time Select (D6, D5, D4). Bits 6, 5, and 4 determine the time-out period. Table 13 indicates the range of time-out values that can be obtained. The default values of D6, D5, and D4 are 001, which sets the WDT to its minimum time-out period when coming out of $\overline{\text{RESET}}$.

WDT During HALT (D7). This bit determines whether or not the WDT is active during HALT mode. A 1 indicates active during HALT mode. A 0 prevents the WDT from resetting the part while halted. Coming out of $\overline{\text{RESET}}$, the WDT is enabled during HALT mode.

STOP MODE (D3). Coming out of $\overline{\text{RESET}}$, the device STOP mode is disabled. If an application requires use of STOP mode, bit D3 must be cleared immediately at leaving $\overline{\text{RESET}}$. If bit D3 is set, the STOP instruction executes as a NOP. If bit D3 is cleared, the STOP instruction enters STOP mode.

Bits 2, 1 and 0. These bits are reserved and must be 0.

Table 13. WDT Time-Out

D6	D5	D4	Crystal Clocks* to Timeout	Time-Out Using a 10-MHz Crystal
0	0	0	Disabled	Disabled
0	0	1	65,536 TpC	6.55 ms
0	1	0	131,072 TpC	13.11 ms
0	1	1	262,144 TpC	26.21 ms
1	0	0	524,288 TpC	52.43 ms
1	0	1	1,048,576 TpC	104.86 ms
1	1	0	2,097,152 TpC	209.72 ms
1	1	1	8,388,608 TpC	838.86 ms

Note: *TpC is an XTAL clock cycle. The default at reset is 001.

POWER-DOWN MODES

In addition to the standard RUN mode, the Z8Plus MCU supports two Power-Down modes to minimize device current consumption. The two modes supported are HALT and STOP.

HALT MODE OPERATION

The HALT mode suspends instruction execution and turns off the internal CPU clock. The on-chip oscillator circuit remains active so the internal clock continues to run and is applied to the timers and interrupt logic.

To enter HALT mode, the device only requires a HALT instruction. It is *not* necessary to execute a NOP instruction immediately before the HALT instruction.

```
7F    HALT        ; enter HALT mode
```

HALT mode can be exited by servicing an external or internal interrupt. The first instruction executed is the interrupt service routine. At completion of the interrupt service routine, the user program continues from the instruction after the HALT instruction.

The HALT mode can also be exited via a $\overline{\text{RESET}}$ activation or a Watch-Dog Timer (WDT) time-out. In these cases, program execution restarts at 0020H, the reset restart address.

CLOCK

The Z8Plus MCU derives its timing from on-board clock circuitry connected to pins XTAL1 and XTAL2. The clock circuitry consists of an oscillator, a glitch filter, and a divide-by-two shaping circuit. Figure 12 illustrates the clock circuitry. The oscillator's input is XTAL1 and its output is XTAL2. The clock can be driven by a crystal, a ceramic resonator, LC clock, or an external clock source.

By selecting the RC OSCILLATOR option in the graphical user interface (GUI), the circuit may instead be driven by an external Resistor and Capacitor (RC) oscillator. Figure 13 illustrates this configuration. This design is limited to no more than 4 MHz to restrict EMI noise.

Note: The reduced drive strength of this configuration also allows the clock circuit to use a micropower-type crystal (also known as a tuning fork) without reduction resistors.

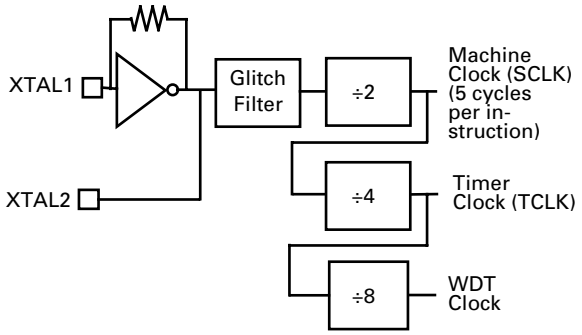


Figure 12. Clock Circuit

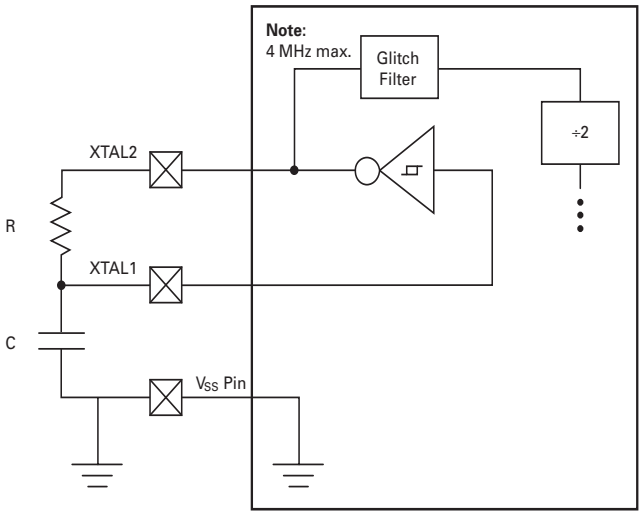


Figure 13. Z8Plus in RC Oscillator Mode

OSCILLATOR OPERATION

The Z8Plus MCU uses a Pierce oscillator with an internal feedback resistor (Figure 14). The advantages of this circuit are low-cost, large output signal, low-power level in the crystal, stability with respect to V_{CC} and temperature, and low impedances (not disturbed by stray effects).

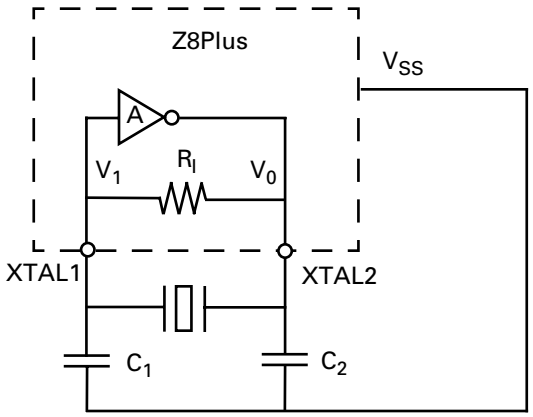


Figure 14. Pierce Oscillator with Internal Feedback Circuit

One drawback to the Pierce oscillator is the requirement for high gain in the amplifier to compensate for feedback path losses. The oscillator amplifies its own noise at start-up until it settles at the frequency that satisfies the gain/phase requirements. A x B = 1; where A = VO/VI is the gain of the amplifier, and B = VI/VO is the gain of the feedback element. The total phase shift around the loop is forced to 0 (360 degrees). V_{IN} must be in phase with itself; therefore, the amplifier/inverter provides a 180-degree phase shift, and the feedback element is forced to provide the other 180-degree phase shift.

R1 is a resistive component placed from output to input of the amplifier. The purpose of this feedback is to bias the amplifier in its linear region and provide the start-up transition.

Capacitor C2, combined with the amplifier output resistance, provides a small phase shift. It also provides some attenuation of overtones.

Capacitor C_1, combined with the crystal resistance, provides an additional phase shift.

Start-up time may be affected if C_1 and C_2 are increased dramatically in size. As C_1 and C_2 increase, the start-up time increases until the oscillator reaches a point where it ceases to operate.

For fast and reliable oscillator start-up over the manufacturing process range, the load capacitors should be sized as low as possible without resulting in overtone operation.

Layout

Traces connecting crystal, caps, and the Z8Plus oscillator pins should be as short and wide as possible to reduce parasitic inductance and resistance. The components (caps, the crystal, and resistors) should be placed as close as possible to the oscillator pins of the Z8Plus.

The traces from the oscillator pins of the integrated circuit (IC) and the ground side of the lead caps should be guarded from all other traces (clock, V_{CC}, address/data lines, and system ground) to reduce cross talk and noise injection. Guarding is usually accomplished by keeping other traces and system ground trace planes away from the oscillator circuit, and by placing a Z8Plus device V_{SS} ground ring around the traces/components. The ground side of the oscillator lead caps should be connected to a single trace to the Z8Plus device V_{SS} (GND) pin. It should not be shared with any other system-ground trace or components except at the Z8Plus device V_{SS} pin. The objective is to prevent differential system ground noise injection into the oscillator (Figure 15).

Indications of an Unreliable Design

There are two major indicators that are used in working designs to determine their reliability over full lot and temperature variations. They are:

Start-Up Time. If start-up time is excessive, or varies widely from unit to unit, there is probably a gain problem. To fix the problem, the C_1 and C_2 capacitors require reduction. The amplifier gain is either not adequate at frequency, or the crystal R's are too large.

Output Level. The signal at the amplifier output should swing from ground to V_{CC} to indicate adequate gain in the amplifier. As the oscillator starts up, the signal amplitude grows until clipping occurs. At that point, the loop gain is effectively reduced to unity, and constant oscillation is achieved. A signal of less than 2.5 volts peak-to-peak is an indication that low gain can be a problem. Either C_1 or C_2 should be made smaller, or a low-resistance crystal should be used.

LC OSCILLATOR

The Z8Plus oscillator can use an inductor capacitor oscillator (LC) network to generate an XTAL clock (Figure 17).

The frequency stays stable over V_{CC} and temperature. The oscillation frequency is determined by the equation:

$$\text{Frequency} = \frac{1}{2\pi (LC_T)^{1/2}}$$

where L is the total inductance including parasitics, and C_T is the total series capacitance including parasitics.

Simple series capacitance is calculated using the equation at the top of the next column.

$$1/C_T = 1/C_1 + 1/C_2$$
$$\text{If } C_1 = C_2$$
$$1/C_T = 2/C_1$$
$$C_1 = 2C_T$$

A sample calculation of capacitance C_1 and C_2 for 5.83-MHz frequency and inductance value of 27 µH is displayed as follows:

$$5.83\ (10\text{^}6) = \frac{1}{2\pi [27\ (10^{-6})\ C_T]^{1/2}}$$

$$C_T = 27.6 \text{ pF}$$

Thus, C_1 = 55.2 pF and C_2 = 55.2 pF.

TIMERS

Two 8-bit timers, timer 0 (T0) and timer 1 (T1) are available to function as a pair of independent 8-bit standard timers. They may also be cascaded to function as a 16-bit Pulse-Width Modulator (PWM) timer. Two additional 8-bit timers (T2 and T3) are provided, but they can only operate as one 16-bit standard timer.

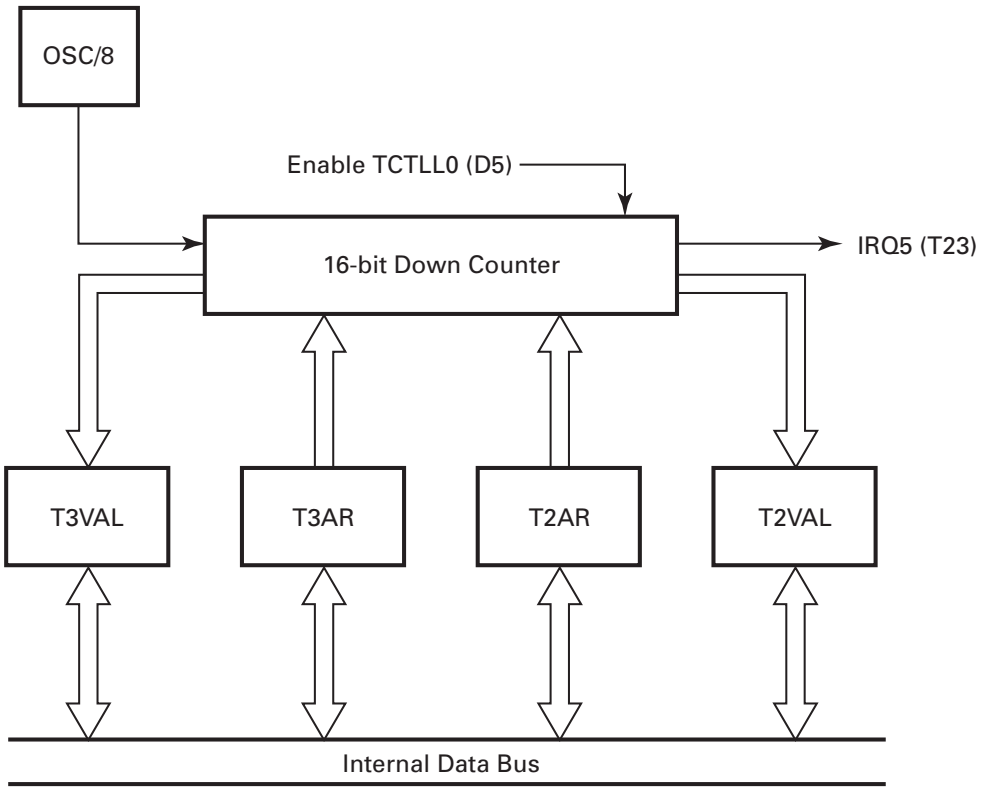


Figure 19. 16-Bit Standard Timer

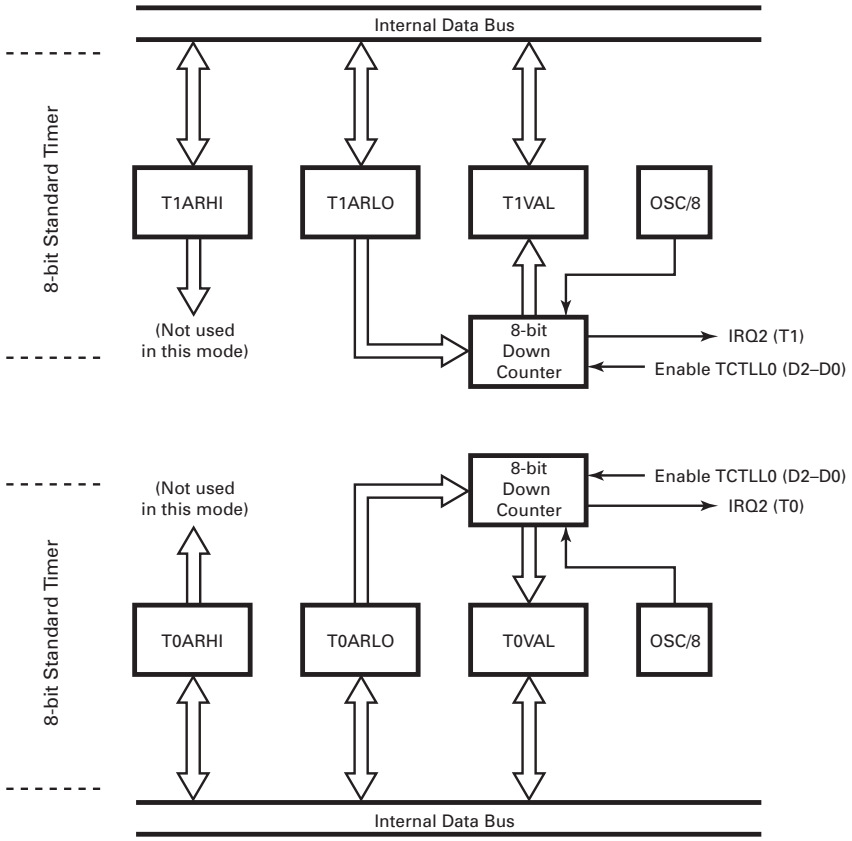


Figure 20. 8-Bit Standard Timers

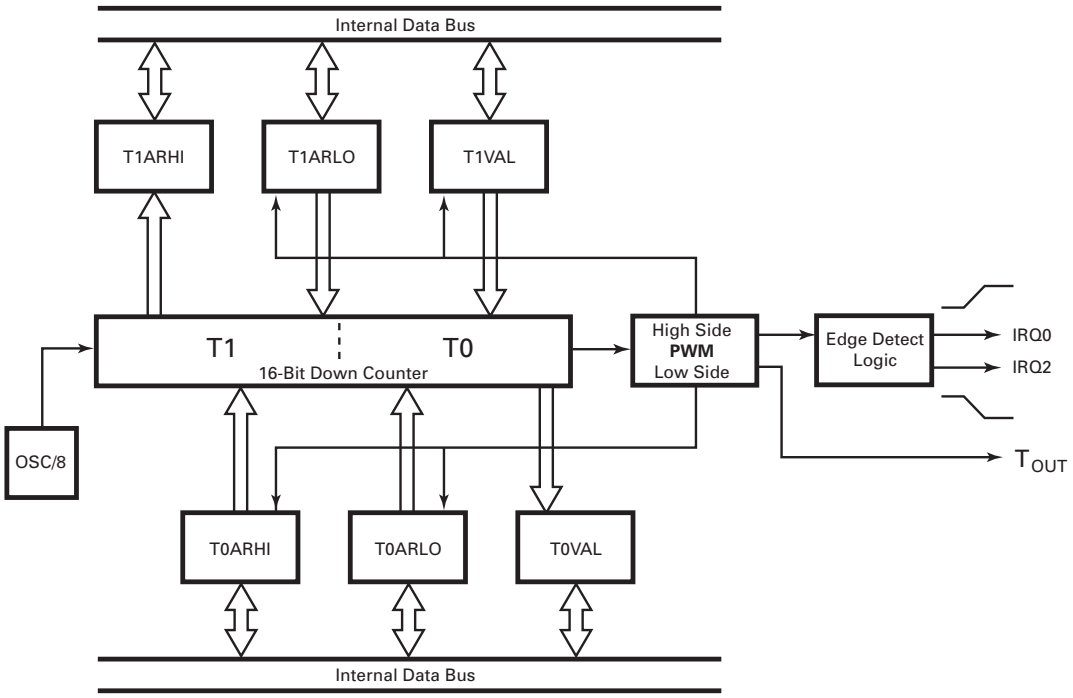


Figure 21. 16-Bit Standard PWM Timer

PORT B

Port B Description

Port B is a 6-bit (bidirectional), CMOS-compatible I/O port. These six I/O lines can be configured under software control to be an input or output. Each bit is configured independently from the other bits. That is, one bit may be set to INPUT while another bit is set to OUTPUT.

In addition to standard input/output capability, five pins of Port B provide special functionality as indicated in Table 15.

Table 15. Port B Special Functions

Port Pin	Input Special Function	Output Special Function
PB0	Stop Mode Recovery Input	None
PB1	None	T0 Output
PB2	IRQ3	None
PB3	Comparator Reference Input	None
PB4	Comparator Signal Input/IRQ1/IRQ4	None

Special functionality is invoked via the Port B special function register. Port B, bit 5, is an open-drain-only pin when in output mode. There is no high-side driver on the output stage, nor is there any high-side protection device, because PB5 acts as the V_{PP} pin for EPROM programming mode. The user should always place an external protection diode on this pin. See Figure 32.

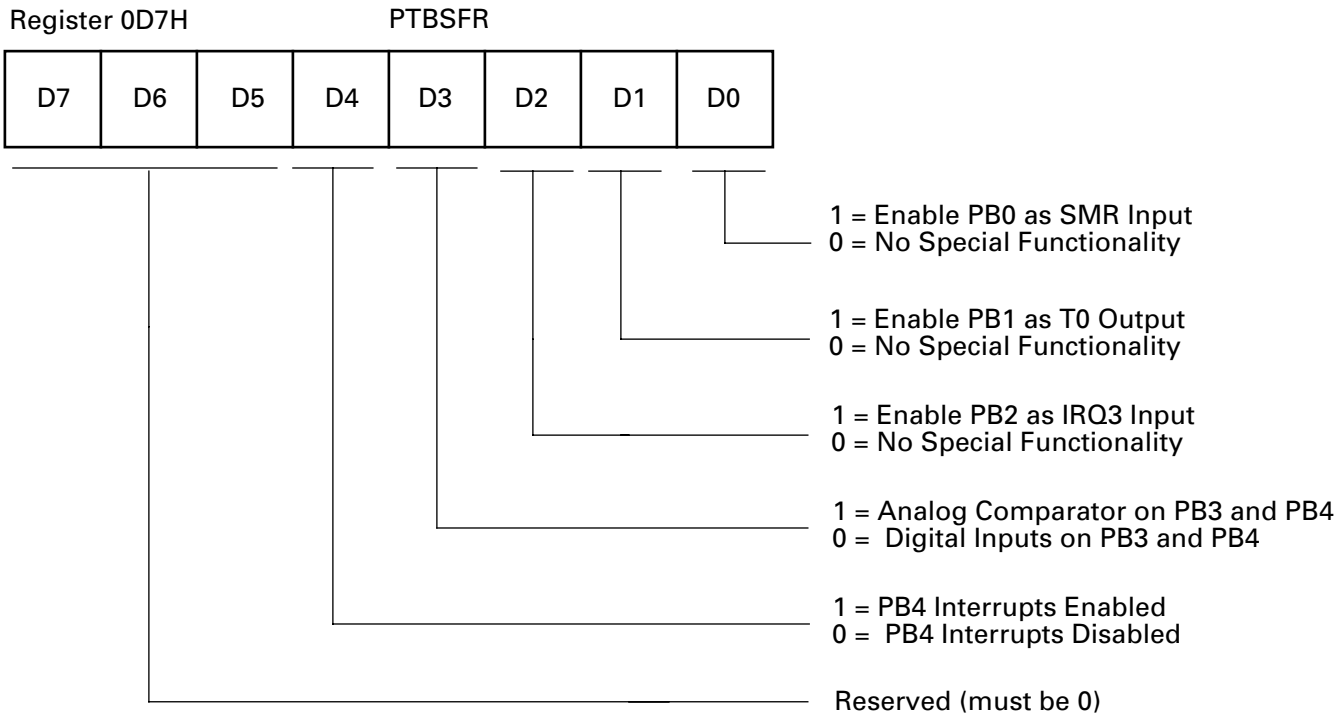


Figure 32. Port B Special Function Register

PORT B—PIN 0 CONFIGURATION

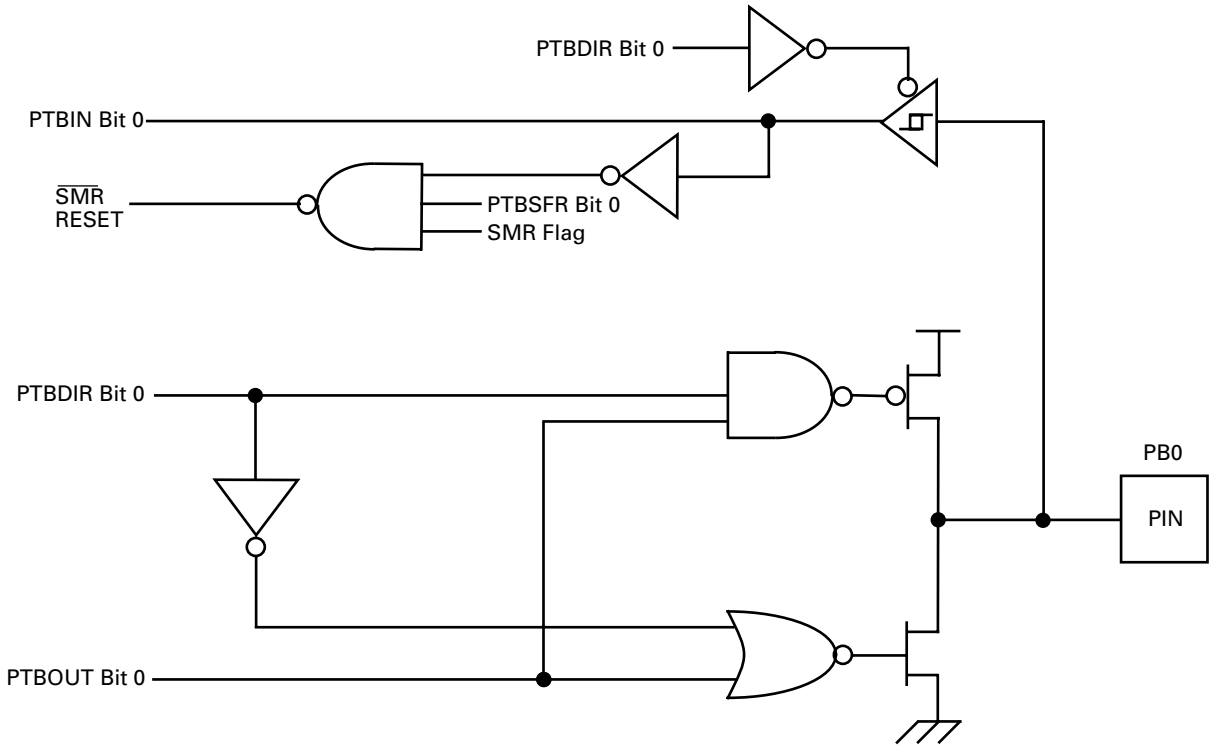
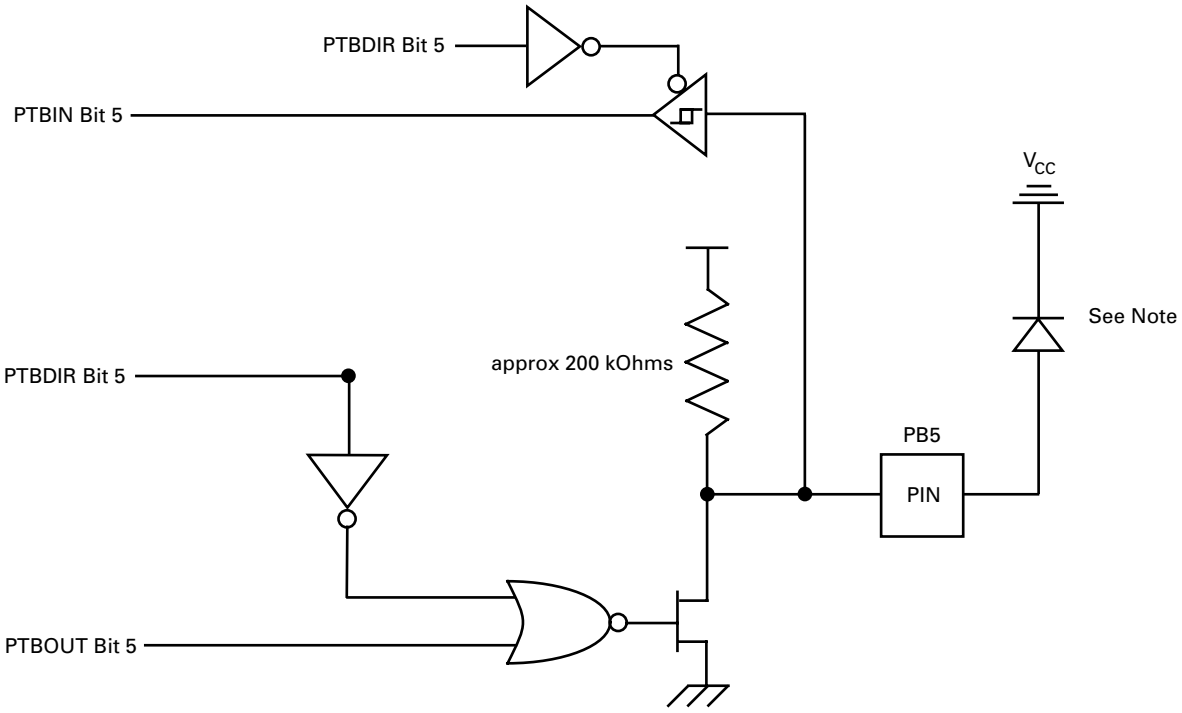


Figure 33. Port B Pin 0 Diagram



Note: There is no high-side protection device. The user should always place an external protection diode as shown.

Figure 34. Port B Pin 5 Diagram

PORT B—PIN 1 CONFIGURATION

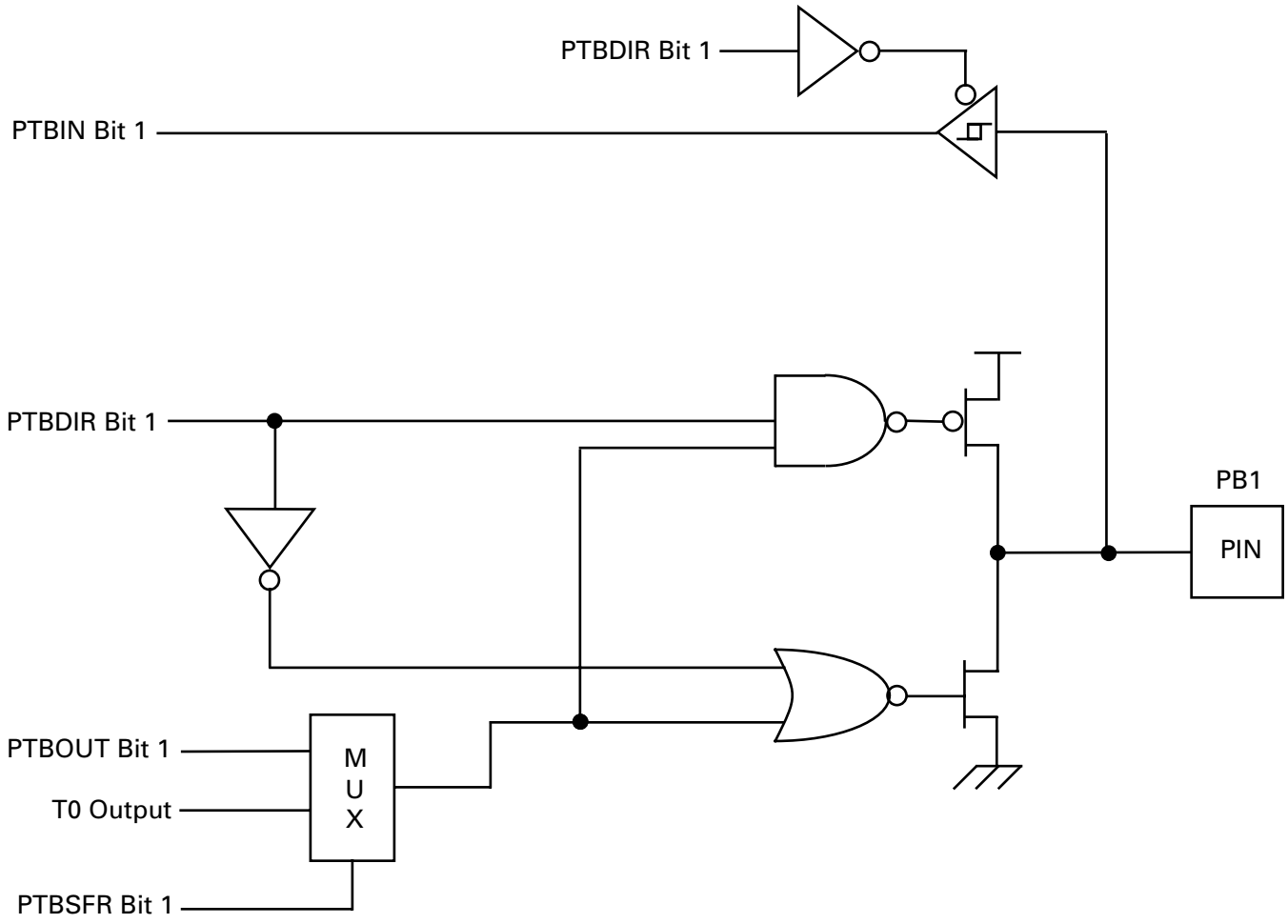


Figure 35. Port B Pin 1 Diagram

PORT B—PINS 3 AND 4 CONFIGURATION

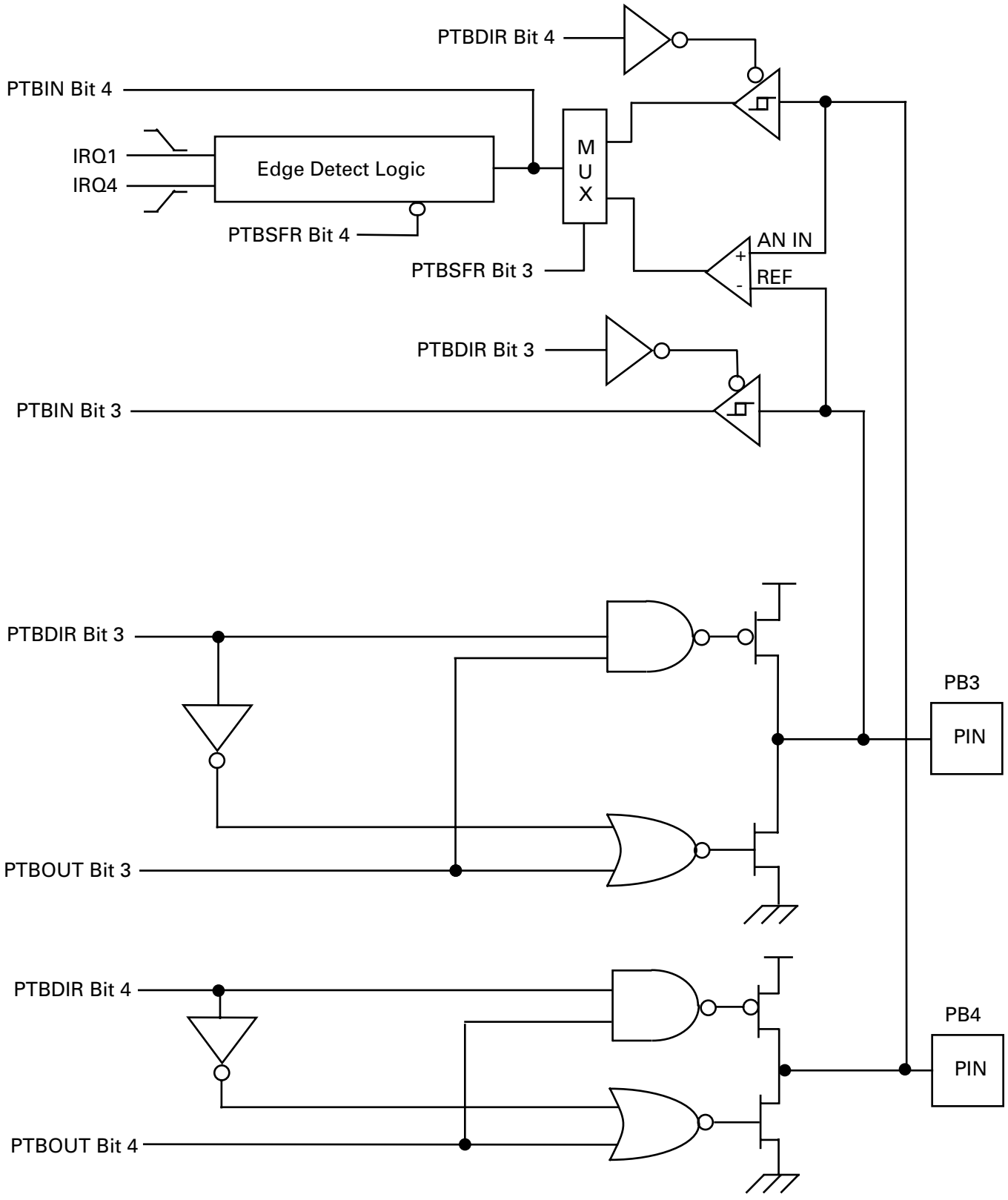


Figure 37. Port B Pins 3 and 4 Diagram

PORT B CONTROL REGISTERS

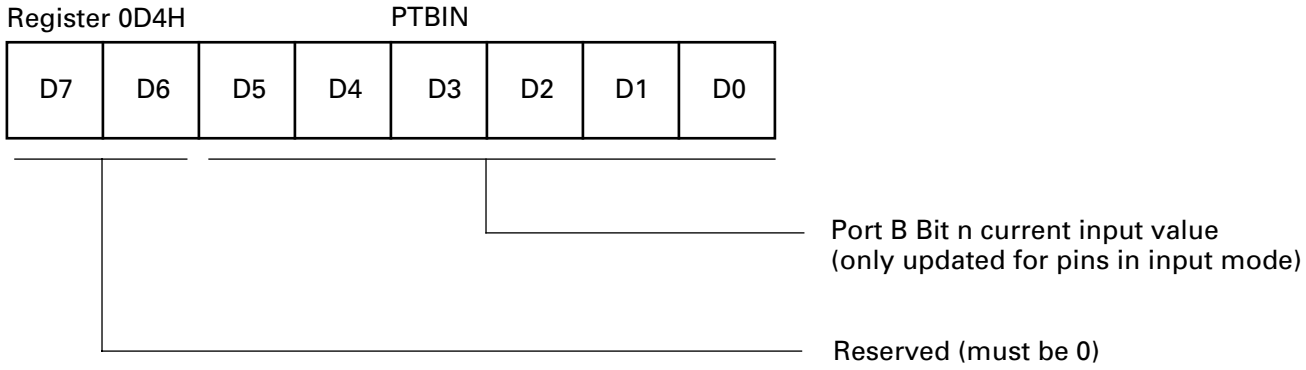


Figure 38. Port B Input Value Register

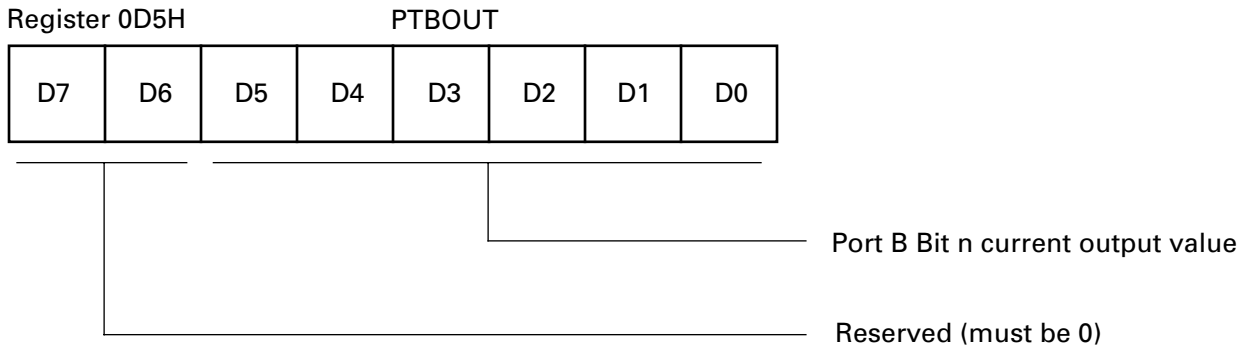


Figure 39. Port B Output Value Register

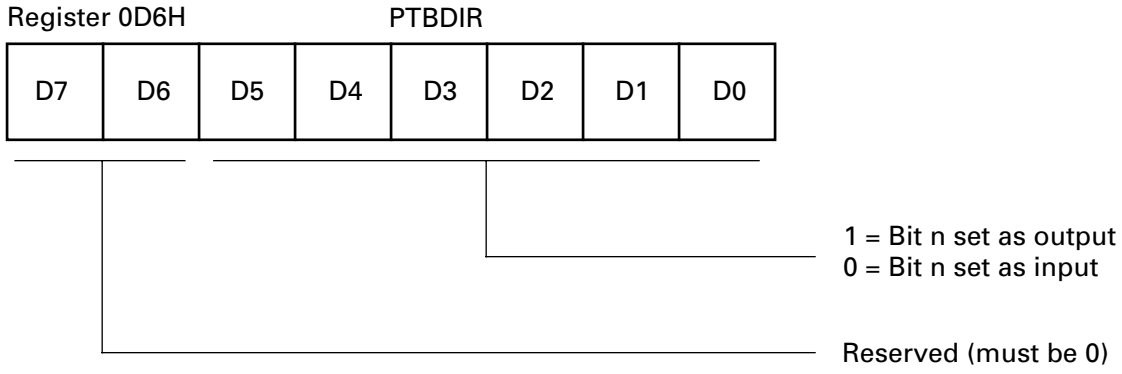


Figure 40. Port B Directional Control Register

INPUT PROTECTION

All I/O pins feature diode input protection. There is a diode from the I/O pad to V_{CC} and V_{SS} (Figure 43).

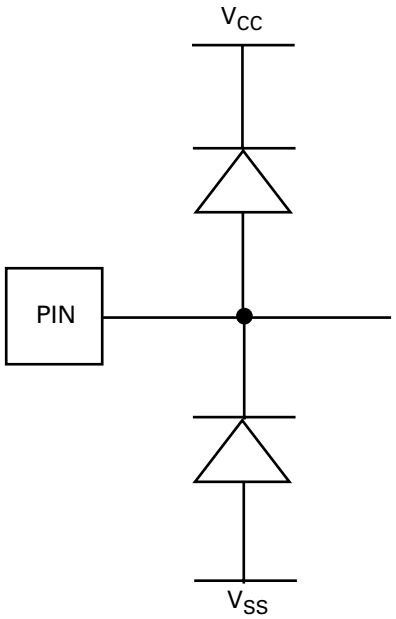


Figure 43. I/O Pin Diode Input Protection

However, the PB5 pin features only the input protection diode, from the pad to V_{SS} (Figure 44).

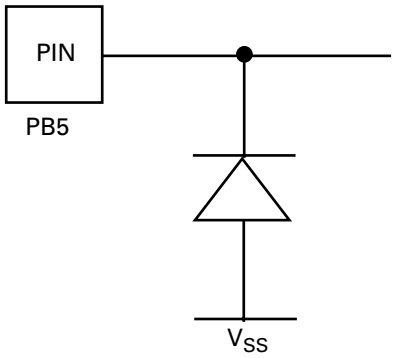
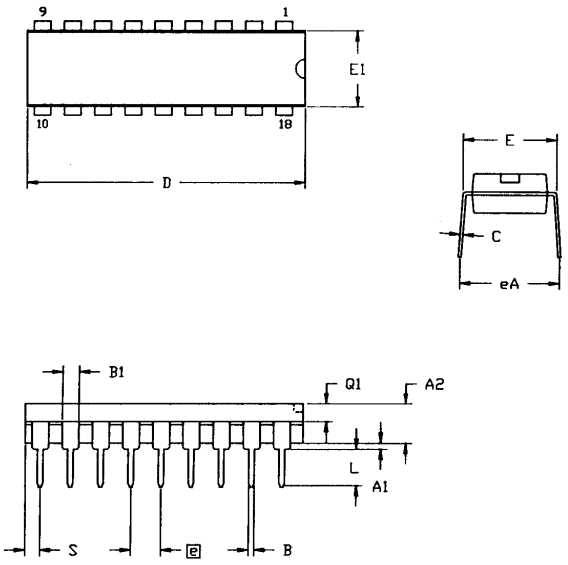


Figure 44. PB5 Pin Input Protection

The high-side input protection diode was removed on this pin to allow the application of high voltage during the OTP programming mode.

For better noise immunity in applications that are exposed to system EMI, a clamping diode to V_{SS} from this pin should be used to prevent entering the OTP programming mode or to prevent high voltage from damaging this pin.

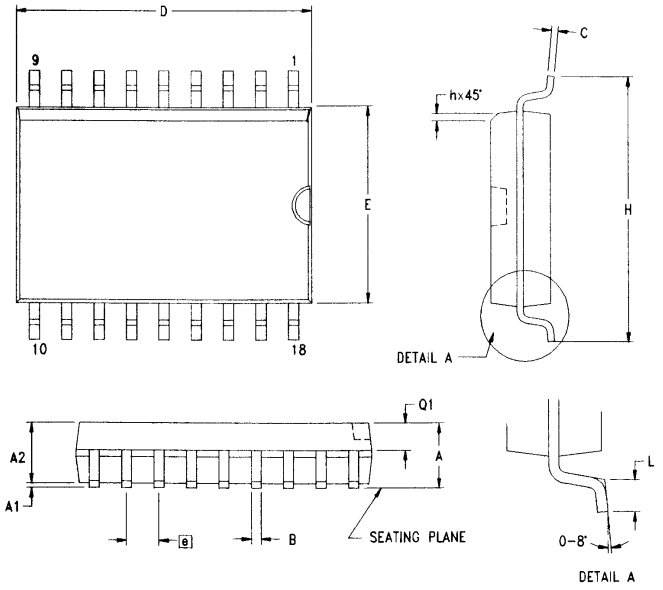
PACKAGE INFORMATION



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	0.81	.020	.032
A2	3.25	3.43	.128	.135
B	0.38	0.53	.015	.021
B1	1.14	1.65	.045	.065
C	0.23	0.38	.009	.015
D	22.35	23.37	.880	.920
E	7.62	8.13	.300	.320
E1	6.22	6.48	.245	.255
e	2.54 TYP		.100 TYP	
eA	7.87	8.89	.310	.350
L	3.18	3.81	.125	.150
Q1	1.52	1.65	.060	.065
S	0.89	1.65	.035	.065

CONTROLLING DIMENSIONS : INCH

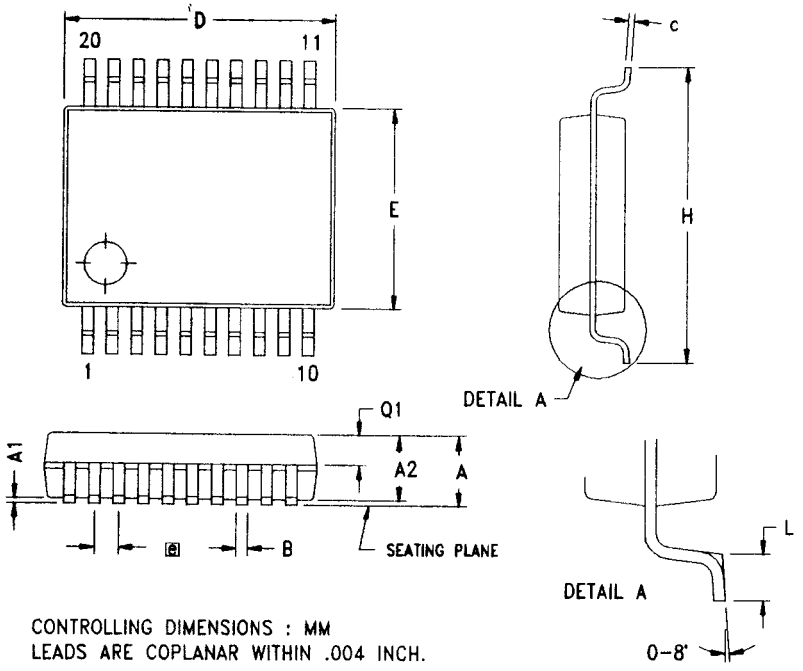
Figure 45. 18-Pin DIP Package Diagram



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	2.40	2.65	0.094	0.104
A1	0.10	0.30	0.004	0.012
A2	2.24	2.44	0.088	0.096
B	0.36	0.46	0.014	0.018
C	0.23	0.30	0.009	0.012
D	11.40	11.75	0.449	0.463
E	7.40	7.60	0.291	0.299
e	1.27 TYP		0.050 TYP	
H	10.00	10.65	0.394	0.419
h	0.30	0.50	0.012	0.020
L	0.60	1.00	0.024	0.039
Q1	0.97	1.07	0.038	0.042

CONTROLLING DIMENSIONS : MM
LEADS ARE COPLANAR WITHIN .004 INCH.

Figure 46. 18-Pin SOIC Package Diagram



SYMBOL	MILLIMETER			INCH		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.73	1.85	1.98	0.068	0.073	0.078
A1	0.05	0.13	0.21	0.002	0.005	0.008
A2	1.68	1.73	1.83	0.066	0.068	0.072
B	0.25	0.30	0.38	0.010	0.012	0.015
C	0.13	0.15	0.22	0.005	0.006	0.009
D	7.07	7.20	7.33	0.278	0.283	0.289
E	5.20	5.30	5.38	0.205	0.209	0.212
e	0.65 TYP			0.0256 TYP		
H	7.65	7.80	7.90	0.301	0.307	0.311
L	0.56	0.75	0.94	0.022	0.030	0.037
Q1	0.74	0.78	0.82	0.029	0.031	0.032

Figure 47. 20-Pin SSOP Package Diagram